



PRODUCT CHANGE NOTICE

1. TITLE Case Outline Lead Finish, SMD 0.2 style		2. DOCUMENT NUMBER FV5-C-13-002
		3. DATE October 22, 2012
4. MANUFACTURER AND ADDRESS International Rectifier 205 Crawford Street Leominster, MA 01453		5. MANUFACTURER PART NUMBER NA / SMD 0.2 package types
		6. BASE PART NA
		7. NATIONAL STOCK NUMBER (NSN) NA
8. CAGE 69210	9. EFFECTIVE DATE October 23, 2012	10. GOVERNMENT NUMBER NA
11. POINT OF CONTACT Manufacturer's Representative or Customer Service Representative (978) 534-5776		12. DRAWING NUMBER NA
		13. SPECIFICATION NUMBER MIL-PRF-19500
14. PRODUCT CHANGE <p>This GIDEP PCN is to announce a change in the typical Ceramic SMD case outline lead finish. The lead finish for the SMD 0.2 style packages will be changed from gold (Au) plating to hot solder dip (SnPb coating). International Rectifier is adding the extra solder dip step (lead finish) to its SMD 0.2 packaged products as part of its finishing operations.</p> <p>Solder Dip Process Discussion: Part described above will be hot solder dipped in 63 Sn / 37 Pb solder using an automated system. Solder dipping gold-plated leads is a common practice in industry. During this process, the gold is dissolved in the solder bath which allows the solder to adhere to the base metal (nickel). The gold content of the solder bath is carefully monitored to ensure that it never exceeds 0.2% gold in order to prevent gold embrittlement in the solder joints. Solderability is then performed in accordance with MIL-STD-750 requirements to test the leads.</p>  <p>SMD-0.2</p>		
16. APPROVING GOVERNMENT ACTIVITY		
17. GIDEP REPRESENTATIVE Paul Hebert	18. SIGNATURE 	19. DATE October 22, 2012